



Customer Information Notification

202303002I : Datasheet Update to NAFE11388 and NAFE71388
Device Types

Note: This notice is NXP Company
Proprietary.

Issue Date: Mar 26, 2023 **Effective date:** Mar 27, 2023

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Management summary

NAFE11388 and NAFE71388 data sheets were updated to align with current findings in device performance with general edits and text clarifications.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input type="checkbox"/> Other				

PCN Overview Description

Notable Updates:

1. Table 44: SPI timing and char. TA changed from 25C => 40C
2. TOC for NAFE71388 only: clock figure should be 9.216MHZ
3. Figure 44: add typical application block diagram description.
4. Updated section 7.3.4: Multi-channel selection table for LV_MUX
5. Section 8.2 Table 32: ESD/LU rating reflecting product performance in a safer range.

For a complete listing of changes, see the updated Revision History page in each datasheet.

Reason

- 1 & 2. General text corrections
3. Added multiple block diagrams in the datasheet
4. Correct selection coding in table
5. To provide margin between datasheet spec and maximum tested levels.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Inventory unaffected by data sheet change.

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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